

CLAIMS

1. A connection assembly, comprising:
a substrate assembly; and
connection pads disposed on the substrate assembly to form a configuration capable of aligning each of the connection pads with a different terminal of a warped interconnect.
2. A connection assembly as recited in claim 1, wherein one or more of the connection pads are extended to each align with a different terminal of the warped interconnect.
3. A connection assembly as recited in claim 1, wherein one or more of the connection pads are extended to each align with a different terminal of the warped interconnect that is warped at a first end of the interconnect.
4. A connection assembly as recited in claim 1, wherein one or more of the connection pads are extended to each align with a different terminal of the warped interconnect that is warped at both a first end and a second end of the interconnect.

5. A connection assembly as recited in claim 1, wherein one or more of the connection pads has a center that is offset from a line in a direction parallel to a surface of the substrate assembly upon which the connections pads are disposed, the line being defined by a plane perpendicular to the surface of the substrate assembly.

6. A connection assembly as recited in claim 1, wherein the configuration of the connection pads aligns each connection pad with a different terminal of a warped end of the interconnect.

7. A connection assembly as recited in claim 1, wherein the connection pads are solder pads.

8. A connection assembly as recited in claim 1, wherein the substrate assembly is a multilayered ceramic substrate assembly.

9. A connection assembly as recited in claim 1, wherein the warped interconnect is configured to interface at least one of an integrated circuit and an electronic component with the substrate assembly.

10. A connection assembly as recited in claim 1, wherein:

the substrate assembly has at least a first surface upon which the connection pads are disposed; and

the warped interconnect is warped in a direction parallel with the first surface of the substrate assembly.

11. A connection assembly as recited in claim 1, wherein:

the substrate assembly has at least a first surface upon which the connection pads are disposed; and

a first end of the warped interconnect is warped in a direction parallel with the first surface of the substrate assembly.

12. A connection assembly as recited in claim 1, wherein:

the substrate assembly has at least a first surface upon which the connection pads are disposed; and

a first end and a second end of the warped interconnect are both warped in a direction parallel with the first surface of the substrate assembly.

13. A connection assembly, comprising:

a substrate assembly; and

connection pads disposed on the substrate assembly to form a configuration that aligns each of the connection pads with a different terminal of an interconnect such that a center of one or more of the connection pads is offset from a line in a direction parallel to a surface of the substrate assembly upon which the connection pads are disposed, the line being defined by a plane perpendicular to the surface of the substrate assembly.

14. A connection assembly as recited in claim 13, wherein each of the connection pads align with a different terminal of the interconnect that is at least one of warped at a first end of the interconnect and warped at both the first end and a second end of the interconnect.

15. A connection assembly as recited in claim 13, wherein the substrate assembly is a multilayered ceramic substrate assembly with conductive vias, and wherein the connection pads are solder pads each configured to form a soldered connection that electrically couples a terminal of the interconnect with a conductive via in the substrate assembly.

16. A connection assembly as recited in claim 13, wherein the interconnect is configured to interface at least one of an integrated circuit and an electronic component with the substrate assembly.

17. A connection assembly as recited in claim 13, wherein:

the substrate assembly has a first surface upon which the connection pads are disposed; and

the interconnect has non-linearly positioned terminals.

18. A substrate assembly, comprising:

conductive vias configured to electrically couple electronic components;

a first surface; and

connection pads disposed on the first surface to form a configuration such that each connection pad is configured to align with a different terminal of an interconnect that is warped in a direction parallel with the first surface, the connection pads each configured to couple a different terminal of the interconnect with a conductive via.

19. A substrate assembly as recited in claim 18, wherein the connection pads are solder pads each configured to form a soldered connection that electrically couples a terminal of the interconnect with a conductive via.

20. A method, comprising:
forming a substrate assembly having conductive vias;
determining a warp variance of manufactured interconnects; and
disposing connection pads over the substrate assembly in a configuration according to the warp variance such that each of the connection pads are configured to align with a different terminal of a warped interconnect.

21. A method as recited in claim 20, wherein disposing the connection pads over the substrate assembly includes extending one or more of the connection pads such that each of the connection pads are configured to align with a different terminal of the warped interconnect.

22. A method as recited in claim 20, wherein disposing the connection pads includes forming the connection pads as solder pads each configured to form a soldered connection that electrically couples a terminal of the warped interconnect with a conductive via in the substrate assembly.

23. A method as recited in claim 20, wherein forming the substrate assembly includes forming the substrate assembly as a multilayered ceramic substrate assembly.

24. A method as recited in claim 20, wherein:

forming the substrate assembly includes forming the substrate assembly with at least a first surface; and

disposing the connection pads includes disposing the connection pads on the first surface of the substrate assembly such that each connection pad is configured to align with a different terminal of the warped interconnect which is warped in a direction parallel with the first surface of the substrate assembly.

25. A method as recited in claim 20, wherein:

forming the substrate assembly includes forming the substrate assembly with at least a first surface; and

disposing the connection pads includes disposing the connection pads on the first surface of the substrate assembly such that each connection pad is configured to align with a different terminal of the warped interconnect which has a first end that is warped in a direction parallel with the first surface of the substrate assembly.

26. A method as recited in claim 20, wherein:

forming the substrate assembly includes forming the substrate assembly with at least a first surface; and

disposing the connection pads includes disposing the connection pads on the first surface of the substrate assembly such that each connection pad is configured to align with a different terminal of the warped interconnect which has a first end and a second end that are both warped in a direction parallel with the first surface of the substrate assembly.